



Materials Declaration

Package	Sidebrazed
Body Size	300 mils
Lead Count	14
Option	SnPb

Comsolid

Item	% of Comsolid	Weight (g)	PPM
Kovar	92	1.63E-01	125791
Nickel	4	7.08E-03	5469
Gold	4	7.08E-03	5469
Subtotal		1.77E-01	136730

Lid Frame

Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	1.19 E-02	9221
Sn	20.42	3.06 E-03	2366
Subtotal		1.50 E-02	11587

Ceramic Package

Item	% of Ceramic	Weight (g)	PPM
Al2O3	77.0	8.19 E-01	632880
Iron	6.3	6.71 E-02	51863
Nickel	4.9	5.17 E-02	39945
Chromium	3.3	3.52 E-02	27206
SiO2	3.0	3.21 E-02	24822
Co,Ag,Cu,MgO,CaO	2.9	3.06 E-02	23671
Tungsten	2.5	2.66 E-02	20548
Gold	0.2	1.70 E-03	1315
Subtotal		1.06 E+00	822251

Bond Wires

Item	% of Wire	Weight (g)	PPM
Aluminum	100	1.20 E-03	927

Chip 1

Item	% of Chip	Weight (g)	PPM
Si	100	6.70 E-03	5176

Solder

Item	% of Solder	Weight (g)	PPM
Tin	63	1.83 E-02	14113
Lead	37	1.07 E-02	8289
Subtotal		2.90 E-02	22402

Die Attach Paste

Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80	9.60 E-04	742
Cyanate ester resin	20	2.40 E-04	185
Subtotal		1.20 E-03	927

Package Totals

Weight (g)	PPM
1.29E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary





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Package	Sidebrazed
Body Size	300 mils
Lead Count	14
Option	Pb-free

Combolid

Item	% of Combolid	Weight (g)	PPM
Kovar	92	1.63E-01	117396
Nickel	4	7.08E-03	5104
Gold	4	7.08E-03	5104
Subtotal		1.77E-01	127604

Lid Frame

Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	1.19 E-02	8606
Sn	20.42	3.06 E-03	2208
Subtotal		1.50 E-02	10814

Ceramic Package

Item	% of Ceramic	Weight (g)	PPM
Ceramic			
Al2O3	90.5	7.57 E-01	545440
Cr2O3	3.9	3.26 E-02	23505
SiO2	3.5	2.93 E-02	21094
TiO2	1.0	8.36 E-03	6027
Cao	0.6	5.02 E-03	3616
MgO	0.5	4.18 E-03	3013
Subtotal		8.36 E-01	602696

Metallization			
Tungsten	96.61	4.83 E-02	34824
Molybdenum	3.39	1.70 E-03	1222
Subtotal		5.00 E-02	36046

Lead			
Iron	58	1.51 E-01	108716
Nickel	40.7	1.06 E-01	76289
Manganese	0.8	2.08 E-03	1500
Cobalt	0.5	1.30 E-03	937
Subtotal		2.60 E-01	187441

Ag-Au (base metal)			
Silver	85	8.50 E-03	6128
Copper	15	1.50 E-03	1081
Subtotal		1.00 E-02	7209

Nickel Plating (1st coating)			
Nickel	93.89	9.39 E-03	6769
Palladium	5.36	5.36 E-04	386
Boron	0.7	7.00 E-05	50
Lead	0.05	5.00 E-06	4
Subtotal		1.00 E-02	7209

Nickel Plating (2nd layer)			
Nickel	92	9.20 E-03	6633
Cobalt	8	8.00 E-04	577
Subtotal		1.00 E-02	7209

External Leadframe Plating

Item	% of External Plating	Weight (g)	PPM
Gold	100	1.00 E-02	7209

Bond Wires

Item	% of Wire	Weight (g)	PPM
Aluminum	100	1.20 E-03	865

Chip 1

Item	% of Chip	Weight (g)	PPM
Si	100	6.70 E-03	4830

Die Attach Paste

Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80	9.60 E-04	692
Cyanate ester resin	20	2.40 E-04	173
Subtotal		1.20 E-03	865

Package Totals

Weight (g)	PPM
1.39E+00	1000000

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